

Electronic Patent Application Fee Transmittal

Application Number:	10722838			
Filing Date:	26-Nov-2003			
Title of Invention:	Method of packaging at a wafer level			
First Named Inventor/Applicant Name:	Suan Jeung Boon			
Filer:	Suneel Arora/Amy Moriarty			
Attorney Docket Number:	303.601US3			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180